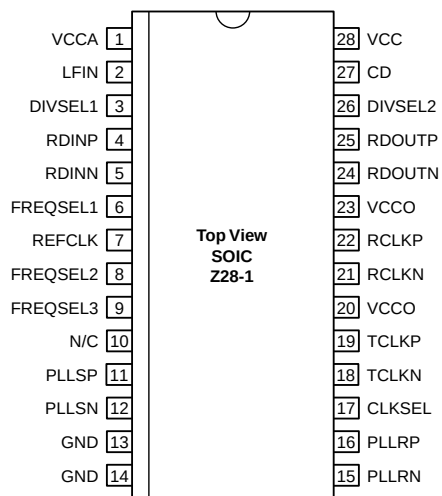
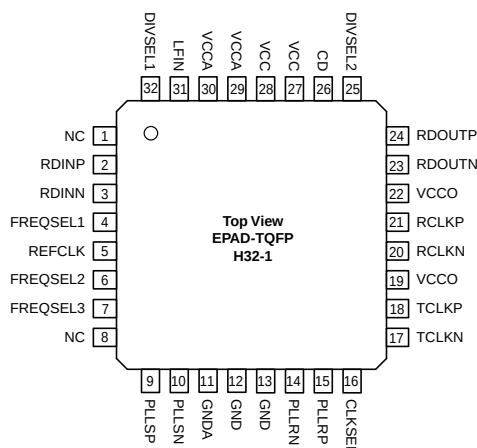


## PACKAGE/ORDERING INFORMATION



**28-Pin SOIC (Z28-1)**



**32-Pin EPAD TQFP (H32-1)**

## Ordering Information<sup>(1)</sup>

| Part Number                       | Package Type | Operating Range | Package Marking                            | Lead Finish    |
|-----------------------------------|--------------|-----------------|--------------------------------------------|----------------|
| SY87701VZC <sup>(3, 4)</sup>      | Z28-1        | Commercial      | SY87701VZC                                 | Sn-Pb          |
| SY87701VZCTR <sup>(2, 3, 4)</sup> | Z28-1        | Commercial      | SY87701VZC                                 | Sn-Pb          |
| SY87701VHC <sup>(3)</sup>         | H32-1        | Commercial      | SY87701VHC                                 | Sn-Pb          |
| SY87701VHCTR <sup>(2, 3)</sup>    | H32-1        | Commercial      | SY87701VHC                                 | Sn-Pb          |
| SY87701VZH <sup>(3, 4)</sup>      | Z28-1        | Commercial      | SY87701VZH with Pb-Free bar line indicator | NiPdAu Pb-Free |
| SY87701VZHTR <sup>(2, 3, 4)</sup> | Z28-1        | Commercial      | SY87701VZH with Pb-Free bar line indicator | NiPdAu Pb-Free |
| SY87701VHH <sup>(3)</sup>         | H32-1        | Commercial      | SY87701VHH with Pb-Free bar line indicator | NiPdAu Pb-Free |
| SY87701VHHTR <sup>(2, 3)</sup>    | H32-1        | Commercial      | SY87701VHH with Pb-Free bar line indicator | NiPdAu Pb-Free |

### Notes:

1. Contact factory for die availability. Dice are guaranteed at  $T_A = 25^\circ\text{C}$ , DC Electricals only.
2. Tape and Reel.
3. Pb-Free package is recommended for new designs.
4. For optimum reliability, care should be taken when using the Z28-1 SOIC package to maintain the package case temperature at or below  $70^\circ\text{C}$ .

## PIN DESCRIPTIONS

### INPUTS

**RDINP, RDINN [Serial Data Input]** Differential PECL.

These built-in line receiver inputs are connected to the differential receive serial data stream. An internal receive PLL recovers the embedded clock (RCLK) and data (RDOUT) information. The incoming data rate can be within one of eight frequency ranges depending on the state of the FREQSEL pins. See “Frequency Selection” Table.

**REFCLK [Reference Clock]** TTL Input.

This input is used as the reference for the internal frequency synthesizer and the “training” frequency for the receiver PLL to keep it centered in the absence of data coming in on the RDIN inputs.

**CD [Carrier Detect]** PECL Input.

This input controls the recovery function of the Receive PLL and can be driven by the carrier detect output of optical modules or from external transition detection circuitry. When this input is HIGH the input data stream (RDIN) is recovered normally by the Receive PLL. When this input is LOW the data on the inputs RDIN will be internally forced to a constant LOW, the data outputs RDOUT will remain LOW, the Link Fault Indicator output LFIN forced LOW and the clock recovery PLL forced to lock onto the clock frequency generated from REFCLK.

**FREQSEL1, ..., FREQSEL3 [Frequency Select]** TTL Inputs.

These inputs select the output clock frequency range as shown in the “Frequency Selection” Table.

**DIVSEL1, DIVSEL2 [Divider Select]** TTL Inputs.

These inputs select the ratio between the output clock frequency (RCLK/TCLK) and the REFCLK input frequency as shown in the “Reference Frequency Selection” Table.

**CLKSEL [Clock Select]** TTL Input.

This input is used to select either the recovered clock of the receiver PLL (CLKSEL = HIGH) or the clock of the frequency synthesizer (CLKSEL = LOW) to the TCLK outputs.

### OUTPUTS

**LFIN [Link Fault Indicator]** TTL Output.

This output indicates the status of the input data stream RDIN. Active HIGH signal is indicating when the internal clock recovery PLL has locked onto the incoming data stream. LFIN will go HIGH if CD is HIGH and RDIN is within the frequency range of the Receive PLL (1000ppm). LFIN is an asynchronous output.

**RDOUTP, RDOUTN [Receive Data Output]** Differential PECL.

These ECL 100K outputs (+3.3V or +5V referenced) represent the recovered data from the input data stream (RDIN). This recovered data is sampled on the rising edge of RCLK.

**RCLKP, RCLKN [Clock Output]** Differential PECL.

These ECL 100K outputs (+3.3V or +5V referenced) represent the recovered clock used to sample the recovered data (RDOUT).

**TCLKP, TCLKN [Clock Output]** Differential PECL.

These ECL 100K outputs (+3.3V or +5V referenced) represent either the recovered clock (CLKSEL = HIGH) used to sample the recovered data (RDOUT) or the transmit clock of the frequency synthesizer (CLKSEL = LOW).

**PLLSP, PLLSN [Clock Synthesis PLL Loop Filter]**

External loop filter pins for the clock synthesis PLL.

**PLLRP, PLLRN [Clock Recovery PLL Loop Filter]**

External loop filter pins for the receiver PLL.

### POWER & GROUND

|                        |                                           |
|------------------------|-------------------------------------------|
| <b>V<sub>CC</sub></b>  | Supply Voltage <sup>(Note 1)</sup>        |
| <b>V<sub>CCA</sub></b> | Analog Supply Voltage <sup>(Note 1)</sup> |
| <b>V<sub>CCO</sub></b> | Output Supply Voltage <sup>(Note 1)</sup> |
| <b>GND</b>             | Ground                                    |
| <b>N/C</b>             | No Connect                                |

**Note 1.** V<sub>CC</sub>, V<sub>CCA</sub>, V<sub>CCO</sub> must be the same value.

## FUNCTIONAL DESCRIPTION

### Clock Recovery

Clock Recovery, as shown in the block diagram generates a clock that is at the same frequency as the incoming data bit rate at the Serial Data input. The clock is phase aligned by a PLL so that it samples the data in the center of the data eye pattern.

The phase relationship between the edge transitions of the data and those of the generated clock are compared by a phase/frequency detector. Output pulses from the detector indicate the required direction of phase correction. These pulses are smoothed by an integral loop filter. The output of the loop filter controls the frequency of the Voltage Controlled Oscillator (VCO), which generates the recovered clock.

Frequency stability without incoming data is guaranteed by an alternate reference input (REFCLK) that the PLL locks onto when data is lost. If the Frequency of the incoming signal varies by greater than approximately 1000ppm with respect to the synthesizer frequency, the PLL will be declared out of lock, and the PLL will lock to the reference clock.

The loop filter transfer function is optimized to enable the PLL to track the jitter, yet tolerate the minimum transition density expected in a received SONET data signal. This transfer function yields a 30 $\mu$ s data stream of continuous 1's or 0's for random incoming NRZ data.

The total loop dynamics of the clock recovery PLL provides jitter tolerance which is better than the specified tolerance in GR-253-CORE.

### Lock Detect

The SY87701V contains a link fault indication circuit which monitors the integrity of the serial data inputs. If the received serial data fails the frequency test, the PLL will be forced to lock to the local reference clock. This will maintain the correct frequency of the recovered clock output under loss of signal or loss of lock conditions. If the recovered clock frequency deviates from the local reference clock frequency by more than approximately 1000ppm, the PLL will be declared out of lock. The lock detect circuit will poll the input data stream in an attempt to reacquire lock to data. If the recovered clock frequency is determined to be within approximately 1000ppm, the PLL will be declared in lock and the lock detect output will go active.

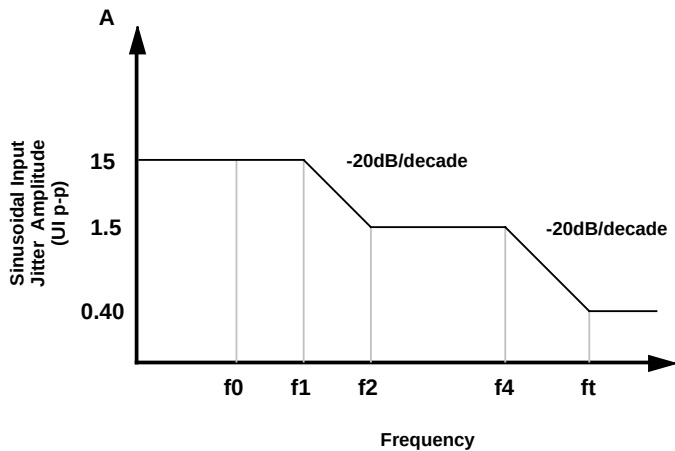
CHARACTERISTICS

Performance

The SY87701V PLL complies with the jitter specifications proposed for SONET/SDH equipment defined by the Bellcore Specifications: GR-253-CORE, Issue 2, December 1995 and ITU-T Recommendations: G.958 document, when used with differential inputs and outputs.

Input Jitter Tolerance

Input jitter tolerance is defined as the peak-to-peak amplitude of sinusoidal jitter applied on the input signal that causes an equivalent 1dB optical/electrical power penalty. SONET input jitter tolerance requirement condition is the input jitter amplitude which causes an equivalent of 1dB power penalty.



| OC/STS-N Level | f0 (Hz) | f1 (Hz) | f2 (Hz) | f3 (kHz) | ft (kHz) |
|----------------|---------|---------|---------|----------|----------|
| 3              | 10      | 30      | 300     | 6.5      | 65       |
| 12             | 10      | 30      | 300     | 25       | 250      |

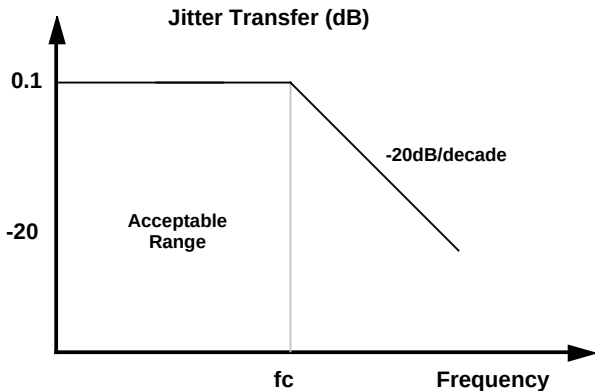
Figure 1. Input Jitter Tolerance

Jitter Transfer

Jitter transfer function is defined as the ratio of jitter on the output OC-N/STS-N signal to the jitter applied on the input OC-N/STS-N signal versus frequency. Jitter transfer requirements are shown in Figure 2.

Jitter Generation

The jitter of the serial clock and serial data outputs shall not exceed .01 U.I. rms when a serial data input with no jitter is presented to the serial data inputs.



| OC/STS-N Level | fc (kHz) | P (dB) |
|----------------|----------|--------|
| 3              | 130      | 0.1    |
| 12             | 225      | 0.1    |

Figure 2. Jitter Transfer

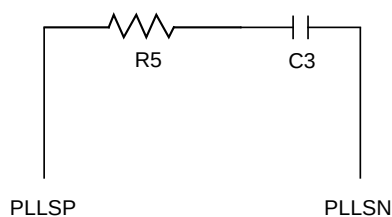
## FREQUENCY SELECTION TABLE

| FREQSEL1 | FREQSEL2 | FREQSEL3 | $f_{VCO}/f_{RCLK}$ | $f_{RCLK}$ Data Rates (Mbps) |
|----------|----------|----------|--------------------|------------------------------|
| 0        | 0        | 0        | 1                  | 750 – 1250                   |
| 0        | 0        | 1        | 2                  | 375 – 625                    |
| 0        | 1        | 0        | 4                  | 188 – 313                    |
| 0        | 1        | 1        | 6                  | 125 – 208                    |
| 1        | 0        | 0        | 8                  | 94 – 157                     |
| 1        | 0        | 1        | 12                 | 63 – 104                     |
| 1        | 1        | 0        | 16                 | 47 – 78                      |
| 1        | 1        | 1        | 24                 | 32 – 52                      |

## REFERENCE FREQUENCY SELECTION

| DIVSEL1 | DIVSEL2 | $f_{RCLK}/f_{REFCLK}$ |
|---------|---------|-----------------------|
| 0       | 0       | 8                     |
| 0       | 1       | 10                    |
| 1       | 0       | 16                    |
| 1       | 1       | 20                    |

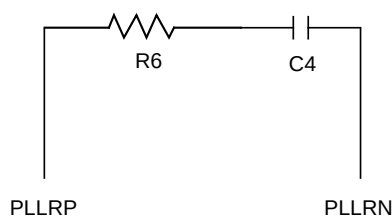
## LOOP FILTER COMPONENTS<sup>(Note 1)</sup>



### Wide Range

R5 = 350Ω

C3 = 1.0μF (X7R Dielectric)



### Wide Range

R6 = 680Ω

C4 = 1.0μF (X7R Dielectric)

**Note 1.** Suggested Values. Values may vary for different applications.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

| Symbol      | Rating                                    | Value            | Unit |
|-------------|-------------------------------------------|------------------|------|
| $V_{CC}$    | Power Supply Voltage                      | –0.5 to +7.0     | V    |
| $V_{IN}$    | Input Voltage                             | –0.5 to $V_{CC}$ | V    |
| $I_{OUT}$   | Output Current<br>– Continuous<br>– Surge | 50<br>100        | mA   |
| $T_{store}$ | Storage Temperature                       | –65 to +150      | °C   |
| $T_A$       | Operating Temperature                     | 0 to +85         | °C   |
| $T_C$       | Case Temperature                          | 0 to +70         | °C   |

**Note 1.** Permanent device damage may occur if “*Absolute Maximum Ratings*” are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to “*Absolute Maximum Ratings*” conditions for extended periods may affect device reliability.

**PACKAGE THERMAL DATA<sup>(1)</sup>**

$\theta_{JA}$  (°C/W) by Velocity (LFPM)

| Package <sup>(1, 2)</sup>       | 0    | 200  | 500  |
|---------------------------------|------|------|------|
| 28-Pin SOIC <sup>(1, 2)</sup>   | 80   | —    | —    |
| 32-Pin EPAD-TQFP <sup>(3)</sup> | 27.6 | 22.6 | 20.7 |

**Note 1.** Case temperature not to exceed 70°C recommended for 28-pin SOIC.

**Note 2.** 28-pin SOIC package is NOT recommended for new designs.

**Note 3.** Using JEDEC standard test boards with die attach pad soldered to PCB. See [www.amkor.com](http://www.amkor.com) for additional package details.

**DC ELECTRICAL CHARACTERISTICS**

$V_{CC} = V_{CCO} = V_{CCA} = 3.3V \pm 5\%$  or  $5.0V \pm 5\%$ ;  $T_A = 0^\circ C$  to  $+85^\circ C$  for 32-TQFP,  $T_C = 0^\circ C$  to  $70^\circ C$  for SOIC.

| Symbol   | Parameter            | Min.         | Typ.       | Max.         | Unit   | Condition |
|----------|----------------------|--------------|------------|--------------|--------|-----------|
| $V_{CC}$ | Power Supply Voltage | 3.15<br>4.75 | 3.3<br>5.0 | 3.45<br>5.25 | V<br>V |           |
| $I_{CC}$ | Power Supply Current | —            | 170        | 230          | mA     |           |

**PECL 100K DC ELECTRICAL CHARACTERISTICS**

$V_{CC} = V_{CCO} = V_{CCA} = 3.3V \pm 5\%$  or  $5.0V \pm 5\%$ ;  $T_A = 0^\circ C$  to  $+85^\circ C$

| Symbol   | Parameter           | Min.             | Typ. | Max.             | Unit    | Condition                      |
|----------|---------------------|------------------|------|------------------|---------|--------------------------------|
| $V_{IH}$ | Input HIGH Voltage  | $V_{CC} - 1.165$ | —    | $V_{CC} - 0.880$ | V       |                                |
| $V_{IL}$ | Input LOW Voltage   | $V_{CC} - 1.810$ | —    | $V_{CC} - 1.475$ | V       |                                |
| $V_{OH}$ | Output HIGH Voltage | $V_{CC} - 1.075$ | —    | $V_{CC} - 0.830$ | V       | $50\Omega$ to $V_{CC} - 2V$    |
| $V_{OL}$ | Output LOW Voltage  | $V_{CC} - 1.860$ | —    | $V_{CC} - 1.570$ | V       | $50\Omega$ to $V_{CC} - 2V$    |
| $I_{IL}$ | Input LOW Current   | 0.5              | —    | —                | $\mu A$ | $V_{IN} = V_{IL}(\text{Min.})$ |

**TTL DC ELECTRICAL CHARACTERISTICS**

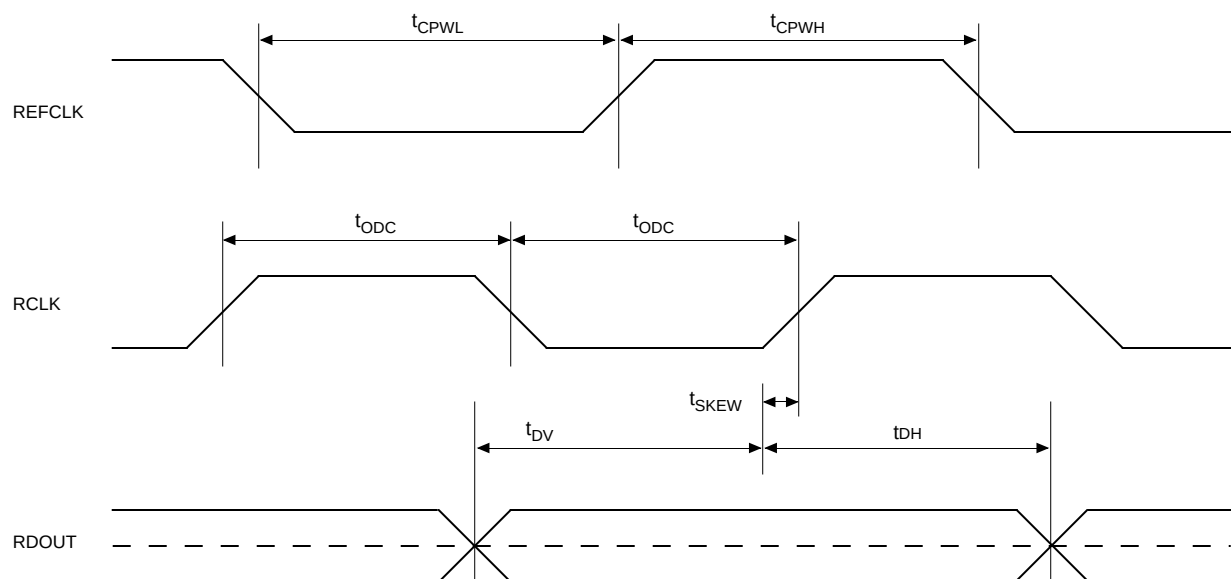
$V_{CC} = V_{CCO} = V_{CCA} = 3.3V \pm 5\%$  or  $5.0V \pm 5\%$ ;  $T_A = 0^\circ C$  to  $+85^\circ C$  for 32-TQFP,  $T_C = 0^\circ C$  to  $70^\circ C$  for SOIC.

| Symbol   | Parameter                    | Min.      | Typ.   | Max.      | Unit               | Condition                                                                        |
|----------|------------------------------|-----------|--------|-----------|--------------------|----------------------------------------------------------------------------------|
| $V_{IH}$ | Input HIGH Voltage           | 2.0       | —      | $V_{CC}$  | V                  |                                                                                  |
| $V_{IL}$ | Input LOW Voltage            | —         | —      | 0.8       | V                  |                                                                                  |
| $V_{OH}$ | Output HIGH Voltage          | 2.0       | —      | —         | V                  | $I_{OH} = -0.4mA$                                                                |
| $V_{OL}$ | Output LOW Voltage           | —         | —      | 0.5       | V                  | $I_{OL} = 4mA$                                                                   |
| $I_{IH}$ | Input HIGH Current           | -175<br>— | —<br>— | —<br>+100 | $\mu A$<br>$\mu A$ | $V_{IN} = 2.7V, V_{CC} = \text{Max.}$<br>$V_{IN} = V_{CC}, V_{CC} = \text{Max.}$ |
| $I_{IL}$ | Input LOW Current            | -300      | —      | —         | $\mu A$            | $V_{IN} = 0.5V, V_{CC} = \text{Max.}$                                            |
| $I_{OS}$ | Output Short Circuit Current | 15        | —      | 100       | mA                 | $V_{OUT} = 0V$ (maximum 1sec)                                                    |

**AC ELECTRICAL CHARACTERISTICS**

$V_{CC} = V_{CCO} = V_{CCA} = 3.3V \pm 5\%$  or  $5.0V \pm 5\%$ ;  $T_A = 0^\circ C$  to  $+85^\circ C$  for 32-TQFP,  $T_C = 0^\circ C$  to  $70^\circ C$  for SOIC.

| Symbol           | Parameter                              | Min.                          | Typ. | Max. | Unit    | Condition                            |
|------------------|----------------------------------------|-------------------------------|------|------|---------|--------------------------------------|
| $f_{VCO}$        | VCO Center Frequency                   | 750                           | —    | 1250 | MHz     | $f_{REFCLK} \times \text{Byte Rate}$ |
| $\Delta f_{VCO}$ | VCO Center Frequency Tolerance         | —                             | 5    | —    | %       | Nominal                              |
| $t_{ACQ}$        | Acquisition Lock Time                  | —                             | —    | 15   | $\mu s$ |                                      |
| $t_{CPWH}$       | REFCLK Pulse Width HIGH                | 4                             | —    | —    | ns      |                                      |
| $t_{CPWL}$       | REFCLK Pulse Width LOW                 | 4                             | —    | —    | ns      |                                      |
| $t_{ir}$         | REFCLK Input Rise Time                 | —                             | 0.5  | 2    | ns      |                                      |
| $t_{ODC}$        | Output Duty Cycle (RCLK/TCLK)          | 45                            | —    | 55   | % of UI |                                      |
| $t_r$<br>$t_f$   | ECL Output Rise/Fall Time (20% to 80%) | 100                           | —    | 500  | ps      | $50\Omega$ to $V_{CC} - 2$           |
| $t_{SKEW}$       | Recovered Clock Skew                   | -200                          | —    | +200 | ps      |                                      |
| $t_{DV}$         | Data Valid                             | $1/(2 \times f_{RCLK}) - 200$ | —    | —    | ps      |                                      |
| $t_{DH}$         | Data Hold                              | $1/(2 \times f_{RCLK}) - 200$ | —    | —    | ps      |                                      |

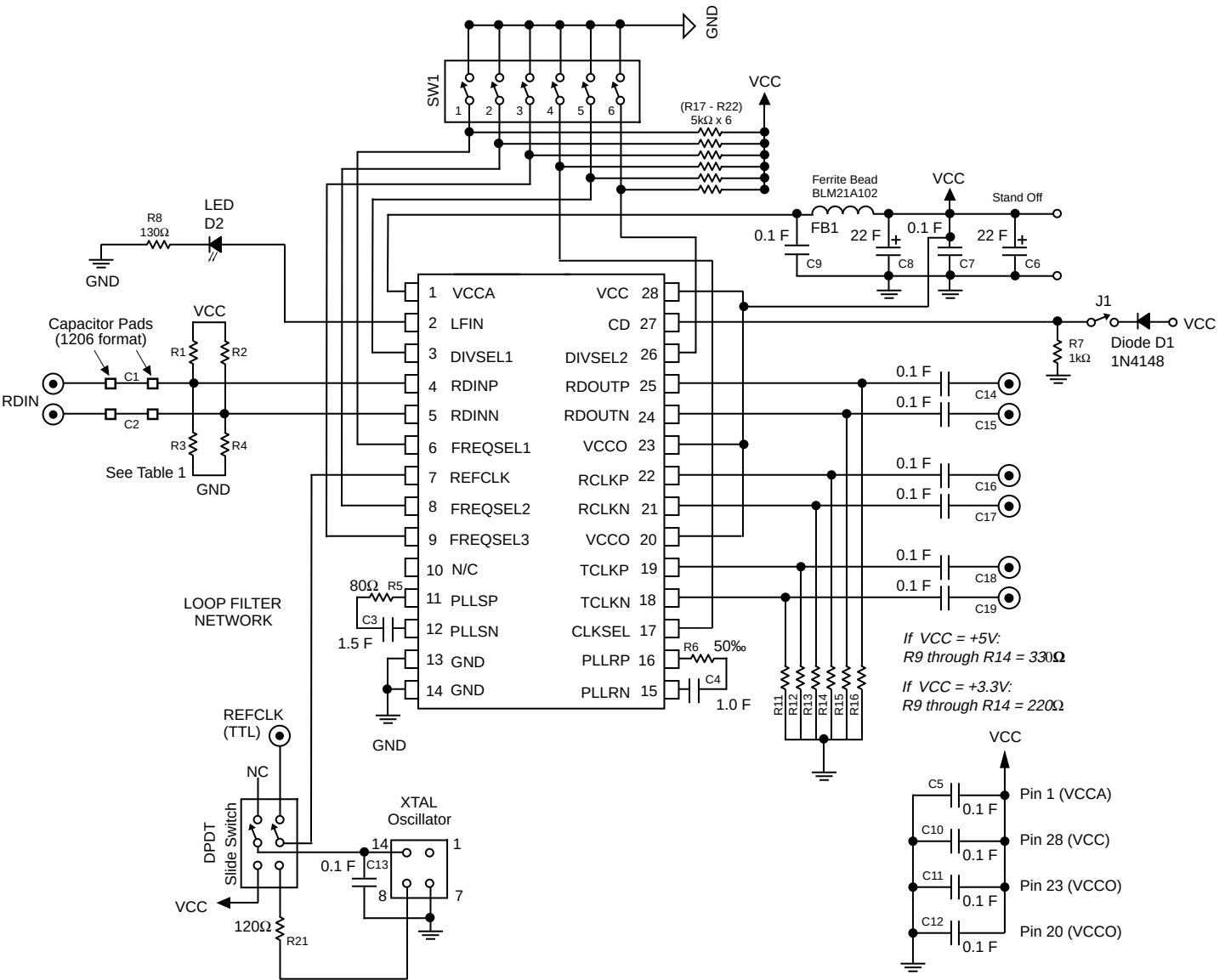
**TIMING WAVEFORMS**



C3, C4 are optional

|                      |
|----------------------|
| C1 = C2 = 1.0μF      |
| R1 = 350Ω            |
| R2 = 680Ω            |
| R3 through R10 = 5kΩ |
| R12 = 12kΩ           |
| R13 = 130Ω           |

28-PIN APPLICATION EXAMPLE



**Note 1.** C5 and C10–C12 are decoupling capacitors and should be kept as close to the power pins as possible.

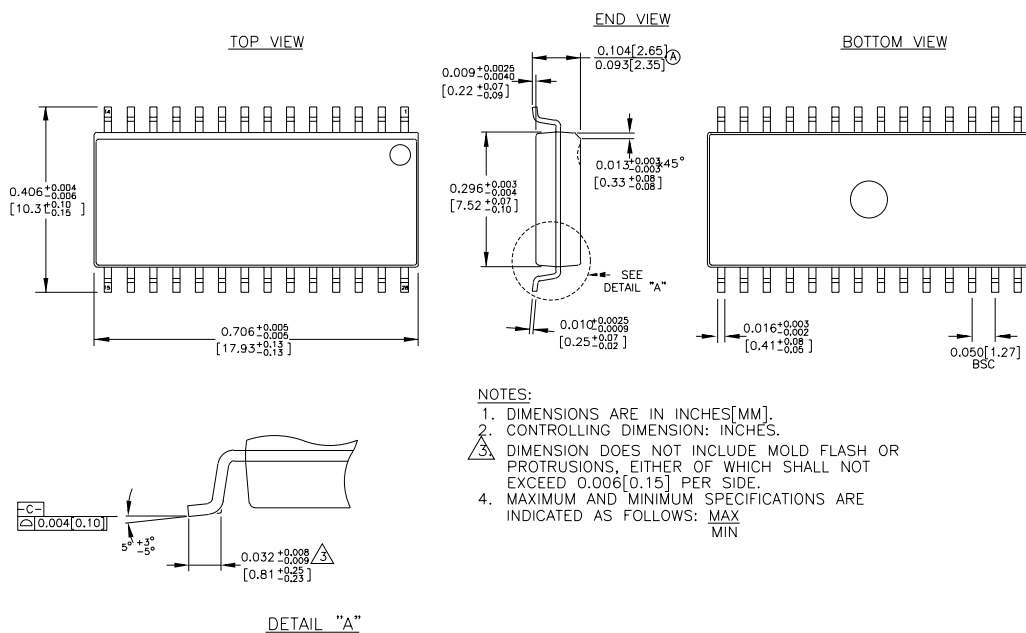
| For AC-Coupling Only |                  | For DC Mode Only  |                   |
|----------------------|------------------|-------------------|-------------------|
| when VCC = +5V       | when VCC = +3.3V | when VCC = +5V    | when VCC = +3.3V  |
| C1 = C2 = 0.1μF      | C1 = C2 = 0.1μF  | C1 = C2 = Shorted | C1 = C2 = Shorted |
| R1 = R2 = 1.2kΩ      | R1 = R2 = 680Ω   | R1 = R2 = 82Ω     | R1 = R2 = 130Ω    |
| R3 = R4 = 3.4kΩ      | R3 = R4 = 1kΩ    | R3 = R4 = 130Ω    | R3 = R4 = 82Ω     |

Table 1.

**BILL OF MATERIALS (32-PIN EPAD-TQFP)**

| Item                                                   | Part Number     | Manufacturer          | Description                                                                   | Qty. |
|--------------------------------------------------------|-----------------|-----------------------|-------------------------------------------------------------------------------|------|
| C1, C2                                                 | VJ0603Y105JXJAT | Vishay                | 1.0μF Ceramic Capacitor, Size 0603<br>X7R Dielectric, Loop Filter, Critical   | 2    |
| C3, C4                                                 | VJ0603Y105JXJAT | Vishay                | 1.0μF Ceramic Capacitor, Size 0603<br>X7R Dielectric, Loop Filter, Optional   | 2    |
| C5                                                     | ECS-T1ED226R    | Panasonic             | 22μF Tantalum Electrolytic Capacitor, Size D                                  | 1    |
| C6                                                     | ECU-V1H104KBW   | Panasonic             | 0.1μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, Power Supply Decoupling | 1    |
| C7, C8, C9, C10                                        | ECS-T1EC685R    | Panasonic             | 6.8μF Tantalum Electrolytic Capacitor, Size C                                 | 4    |
| C19                                                    | ECJ-3YB1E105K   | Panasonic             | 1.0μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, VEEA Decoupling         | 1    |
| C11, C13                                               | ECU-V1H104KBW   | Panasonic             | 0.1μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, VCCO/VCC Decoupling     | 1    |
| C15, C17                                               | ECU-V1H104KBW   | Panasonic             | 0.1μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, VCCA/VEEA Decoupling    | 1    |
| C20                                                    | ECU-V1H104KBW   | Panasonic             | 0.1μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, VEEA Decoupling         | 1    |
| C12, C14                                               | ECU-V1H103KBW   | Panasonic             | 0.01μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, VCCO/VCC Decoupling    | 1    |
| C16, C18                                               | ECU-V1H103KBW   | Panasonic             | 0.01μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, VCCA/VEEA Decoupling   | 1    |
| C21                                                    | ECU-V1H103KBW   | Panasonic             | 0.01μF Ceramic Capacitor, Size 1206<br>X7R Dielectric, VEEA Decoupling        | 1    |
| D1                                                     | 1N4148          |                       | Diode                                                                         | 1    |
| D2                                                     | P300-ND/P301-ND | Panasonic             | T-1 3/4 Red LED                                                               | 1    |
| J1, J2, J3, J4, J5<br>J6, J7, J8, J9,<br>J10, J11, J12 | 142-0701-851    | Johnson<br>Components | Gold Plated, Jack, SMA, PCB Mount                                             | 12   |
| L1, L2, L3                                             | BLM21A102F      | Murata                | Ferrite Beads, Power Noise Suppression                                        | 3    |
| Q1                                                     | NTE123A         | NTE                   | 2N2222A Buffer/Driver Transistor, NPN                                         | 1    |
| R1                                                     |                 |                       | 350Ω Resistor, 2%, Size 0402<br>Loop Filter Component, Critical               | 1    |
| R2                                                     |                 |                       | 680Ω Resistor, 2%, Size 0402<br>Loop Filter Component, Critical               | 1    |
| R3, R4, R5, R6<br>R7, R8, R9, R10                      |                 |                       | 5kΩ Pullup Resistors, 2%, Size 1206                                           | 8    |
| R11                                                    |                 |                       | 1kΩ Pulldown Resistor, 2%, Size 1206                                          | 1    |
| R12                                                    |                 |                       | 12kΩ Resistor, 2%, Size 1206                                                  | 1    |
| R13                                                    |                 |                       | 130Ω Pullup Resistor, 2%, Size 1206                                           | 1    |
| SW1                                                    | 206-7           | CTS                   | SPST, Gold Finish, Sealed Dip Switch                                          | 1    |

## 28 LEAD SOIC .300" WIDE (Z28-1)

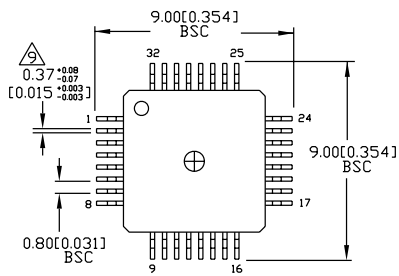


Rev. 02

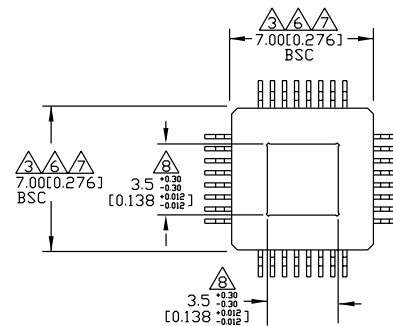
**Note:**

The 28 Lead SOIC package is NOT recommended for new designs.

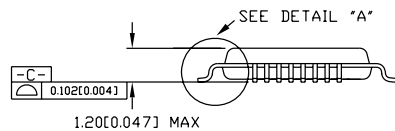
# 32 LEAD EPAD TQFP (DIE UP) (H32-1)



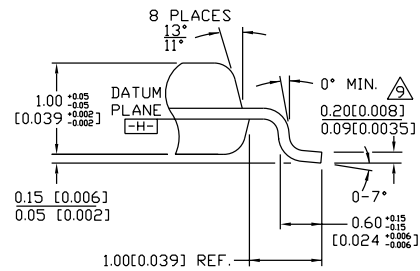
TOP VIEW



BOTTOM VIEW



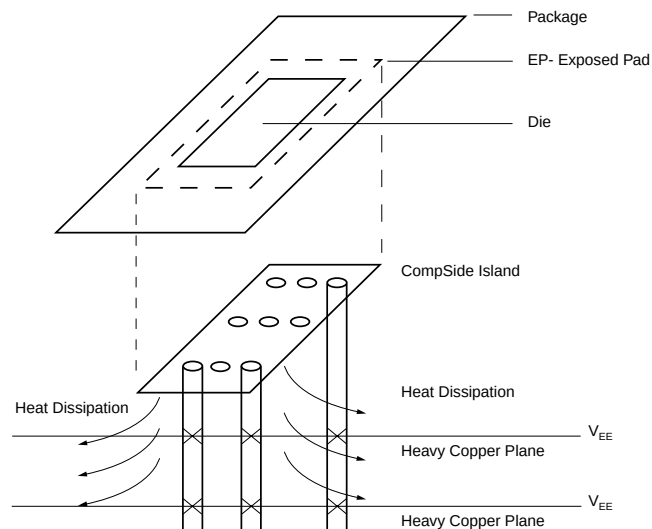
SIDE VIEW



DETAIL "A"

## NOTES:

1. DIMENSIONS ARE IN MM(INCHES).
2. CONTROLLING DIMENSION: MM.
3. DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS, EITHER OF WHICH SHALL NOT EXCEED 0.254 [0.010].
4. LEAD DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
5. MAXIMUM AND MINIMUM SPECIFICATIONS ARE INDICATED AS FOLLOWS: MAX/MIN.
6. THESE DIMENSIONS TO BE DETERMINED AT DATUM PLANE  $\square$ -H.
7. PACKAGE TOP DIMENSIONS ARE SMALLER THAN BOTTOM DIMENSIONS AND TOP OF PACKAGE WILL NOT OVERHANG BOTTOM OF PACKAGE.
8. EXPOSED PAD SHALL BE COPLANAR WITH PACKAGE BOTTOM WITHIN 0.05mm.
9. EXPOSED PAD: Cu WITH Sn/Pb PLATING.
10. DIMENSION INCLUDES LEAD FINISH.



PCB Thermal Consideration for 32-Pin EPAD-TQFP Package

---

## APPENDIX A

### Layout and General Suggestions

1. Establish controlled impedance stripline, microstrip, or co-planar construction techniques.
2. Signal paths should have, approximately, the same width as the device pads.
3. All differential paths are critical timing paths, where skew should be matched to within  $\pm 10\text{ps}$ .
4. Signal trace impedance should not vary more than  $\pm 5\%$ . If in doubt, perform TDR analysis of all high-speed signal traces.
5. Maintain compact filter networks as close to filter pins as possible. Provide ground plane relief under filter path to reduce stray capacitance. Be careful of crosstalk coupling into the filter network.
6. Maintain low jitter on the REFCLK input. Isolate the XTAL oscillator from power supply noise by adequately decoupling. Keep XTAL oscillator close to device, and minimize capacitive coupling from adjacent signals.
7. Higher speed operation may require use of fundamental-tone (third-overtone typically have more jitter) crystal based oscillator for optimum performance. Evaluate and compare candidates by measuring TXCLK jitter.
8. All unused outputs must be terminated. To conserve power, unused PECL outputs can be terminated with a  $1\text{k}\Omega$  resistor to  $V_{EE}$ .

---

**MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA**

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB <http://www.micrel.com>

The information furnished by Micrel in this datasheet is believed to be accurate and reliable. However, no responsibility is assumed by Micrel for its use. Micrel reserves the right to change circuitry and specifications at any time without notification to the customer.

Micrel Products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is at Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.

© 2006 Micrel, Incorporated.